ABSOCIATION CONNECTING ELECTRONICS INDUSTRIES® MOUSTRIES® International and Pan-Ameri	nockburn, Illinois, A	Il rights reserved ur ntions.	nder both lev	nis docume vel parts, th	ent is a declaratio he declaration en	n of the substance compasses all low	es within the manufactur wer level materials for wl	er listed ite hich the m	em. Note: if anufacturer l	the item is an as has engineering	sembly with lower responsibility.	
			Form Type * Distribute	* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information								
Supplier Information												
Company name* Company unique ID				Unique ID Authority				Response Date*				
nsemi									2024-05-16			
Contact Name	Title - Contact			I	Phone - Contact*				Email - Contact*			
Product-Env-Stewards	uct-Env-Stewards Product Enviro Compliance				NA			Product-Env-Stewards@onsemi.com				
Authorized Representative* Title - Representative				I	Phone - Representative*			Email - Representative*				
Product-Env-Stewards Product Enviro Compliance				:	NA				Product-Env-Stewards@onsemi.com			
Requester Item Number Mf	r Item Number	Mfr Item Name			Effective Date	Version	Manufacturing Site		Veight*	UOM	Unit Type	
NC	CV8843MNR2G	3843MNR2G 18L DFN 5X6			2024-05-16		PH1		7.81	mg	Each	
Manufacturing Proccess Information											·	
Terminal Plating / Grid Array Material	rial Terminal Base Alloy J-STD-02		-STD-020 MSL R	ating	Peak Process Body Temperature Max Tir		ture Max Time at Peak	Temperatu	ire Numbe	r of Reflow Cyc	les	
Matte Tin (Sn) - annealed CU Alloy 1					260	С	30	second	ls 3			
Comments												
evel 1 - maximum time at peak temperature duri	ng soldering is 10-3	0 seconds										
for more information regarding material compos	sition please refer to	page 3										

RoHS Material Composition Declaration				Declaration Type *	Detailed					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl ohthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).									
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe y others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of					
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	ances per the definitio	on above	Supplier Acceptance	* Accepted					
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all					
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the					
Supplier Digital Signature Ra	stislav Drska	Le								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3

sigma range of distribution unless otherwise noted).									
Homogeneous Material	al Weight Unit of Measure Level Substance		CAS	Exempt	Weight	Unit of Measure			
Die	3.66	mg	Supplier	Silicon (Si)	7440-21-3		3.66	mg	
Die Attach	0.71	mg	Supplier	Epoxized Condensate Of Para- Hydrobenzaldehyde And Alkyl Phenol	129915-35-1		0.142	mg	
			Supplier	Silver (Ag)	7440-22-4		0.568	mg	
Lead Frame	23.15	mg	Supplier	Silver (Ag)	7440-22-4		0.463	mg	
			Supplier	Iron (Fe)	7439-89-6		0.5093	mg	
			Supplier	Copper (Cu)	7440-50-8		22.1777	mg	
Mold Compound-Black 45	45.98	mg		Epoxy Phenol Resin	proprietary data		4.1382	mg	
			Supplier	Fused Silica (SiO2)	60676-86-0		41.8418	mg	
Plating	3.91	mg	Supplier	Tin (Sn)	7440-31-5		3.91	mg	
Wire Bond - Au	0.4	mg	Supplier	Gold (Au)	7440-57-5		0.4	mg	